

03-11-1999



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To the Honorable Commissioner of Patents and Trad

are attached original documents or copy thereof.

1. Name of conveying party(ies):

Yong-chul OH
Young-Woo PARK

2. Name and address of receiving party(ies):

Name: **Samsung Electronics Co., Ltd.**

Address: **416, Maetan-dong, Paldal-gu, Suwon-city,**

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

City: **Kyungki-do**

State/Prov.: _____

Country: **Republic of Korea**

ZIP: _____

Execution Date: **January 6, 7, 1999**

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: **January 6, 7, 1999**

Patent Application No.

Filing date

B. Patent No.(s)

09/203,670

December 1, 1998

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Susan S. Morse**

Registration No. **35,292**

Address: **Jones, Volentine, Steinberg & Whitt, L.L.P.**

12200 Sunrise Valley Drive

Suite 150

City: **Reston**

State/Prov.: **VA**

Country: **U.S.A.**

ZIP: **20191**

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ **40.00**

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☐ Authorized to be charged to deposit account

8. Deposit account number:

50-0238

40.00 00

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

SUSAN S. MORSE

Name of Person Signing

Signature

MARCH 2, 1999

Date

Total number of pages including cover sheet, attachments, and

3

PATENT

REEL: 9795 FRAME: 0743

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)
of Inventor(s) Yong-chul OH
Young-Woo PARK
_____ and

Insert Name(s)
of Assignee(s) the undersigned hereby sell(s) and assign(s) to
SAMSUNG ELECTRONICS CO., LTD.

Address of 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of
Invention A METHOD OF FORMING AN ISOLATION TRENCH IN A SEMICONDUCTOR DEVICE INCLUDING
ANNEALING AT AN INCREASED TEMPERATURE

Date of Signing
of Application for which an application for patent in the United States of America has been executed by the undersigned
on January 6, 7, 1999

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Raymond C. Jones, Reg. No. 34,631 and Adam C. Volentine, Reg. No. 33,289, members of the firm of JONES & VOLENTINE, L.L.P. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 06 / Jan / 1999, Name of Inventor Yong-chul OH
Yong-chul OH
Date 07 / 01 / 1999, Name of Inventor Young-Woo PARK
Young-Woo PARK
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____

(Note regarding Witnessing and/or Acknowledgment: Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or recorded.)

Witness Kwang - Youl CHUN 7.1.1999
Witness Si - Woo Lee 7. Jan. 1999

ACKNOWLEDGMENT

} ss

This _____ day of _____, 19____, before me
personally came the above-named _____

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL

Official Signature

Official Title

Applicant Reference No.: IE7208-US Atty Docket No.: SEC.566

Serial No.: _____ Filing Date: _____